

ABSTRACT

**METHOD FOR MANUFACTURING A SUBSTRATE
FOR A RADIOFREQUENCY DEVICE**

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The invention relates to a process for fabricating a substrate (7) for a radiofrequency device by joining a piezoelectric layer (3) to a carrier substrate (1) by way of an electrically insulating layer, the piezoelectric layer (3) having a rough surface (30) at its interface with the electrically insulating layer, said process being characterized in that it

10 comprises the following steps:

- providing a piezoelectric substrate (3) having a rough surface (30) suitable for reflecting a radiofrequency wave,

- depositing a dielectric layer (4) on the rough surface (30) of the piezoelectric substrate (3),

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- providing a carrier substrate (1),

- depositing a photo-polymerizable adhesive layer (2) on the carrier substrate,

- bonding the piezoelectric substrate (3) to the carrier substrate (1) by way of the dielectric layer (4) and of the adhesive layer (2), in order to form an assembled substrate (5),

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- irradiating the assembled substrate (5) with a light flux (6) in order to polymerize the adhesive layer (2), said adhesive layer (2) and the dielectric layer (4) together forming the electrically insulating layer.

Figure 5